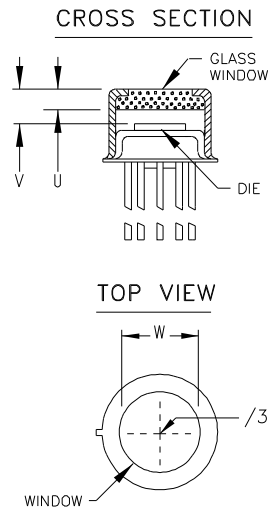
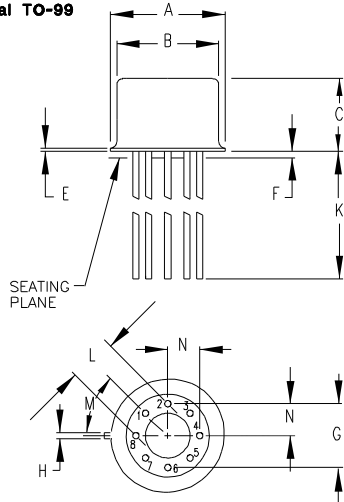


Package Number 001-1 - Metal TO-99



DIM	INCHES		MILLIMETERS		NOTE	DIM	INCHES		MILLIMETERS		NOTE
	MIN.	MAX.	MIN.	MAX.			MIN.	MAX.	MIN.	MAX.	
A	.335	.370	8.51	9.40		V	.058	.077	1.47	1.96	
B	.305	.335	7.75	8.51		W	.246	.254	6.25	6.45	
C	.149	.165	3.79	4.19							
D	.016	.021	0.41	0.53							
E	.010	.040	0.25	1.02							
F	.010	.040	0.25	1.02							
G	.200	BASIC	5.08	BASIC							
H	.028	.034	0.71	0.86							
J	.029	.045	0.74	1.14							
K	.500	--	12.70	--							
L	.110	.160	2.79	4.06							
M	45°	BASIC	45°	BASIC							
N	.095	.105	2.41	2.67							
U	.040	.050	1.02	1.27							

- NOTES:
- LEADS IN TRUE POSITION WITHIN .010" (.25mm) R @ MMC AT SEATING PLANE.
 - PIN NUMBERS SHOWN FOR REFERENCE ONLY. NUMBERS MAY NOT BE MARKED ON PACKAGE.
 - DIE MAY BE ROTATED WITH RESPECT TO INDICATED AXIS.

PACKAGE NUMBER: ZZ001-1 REV.: C
JEDEC NUMBER: UNKNOWN

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